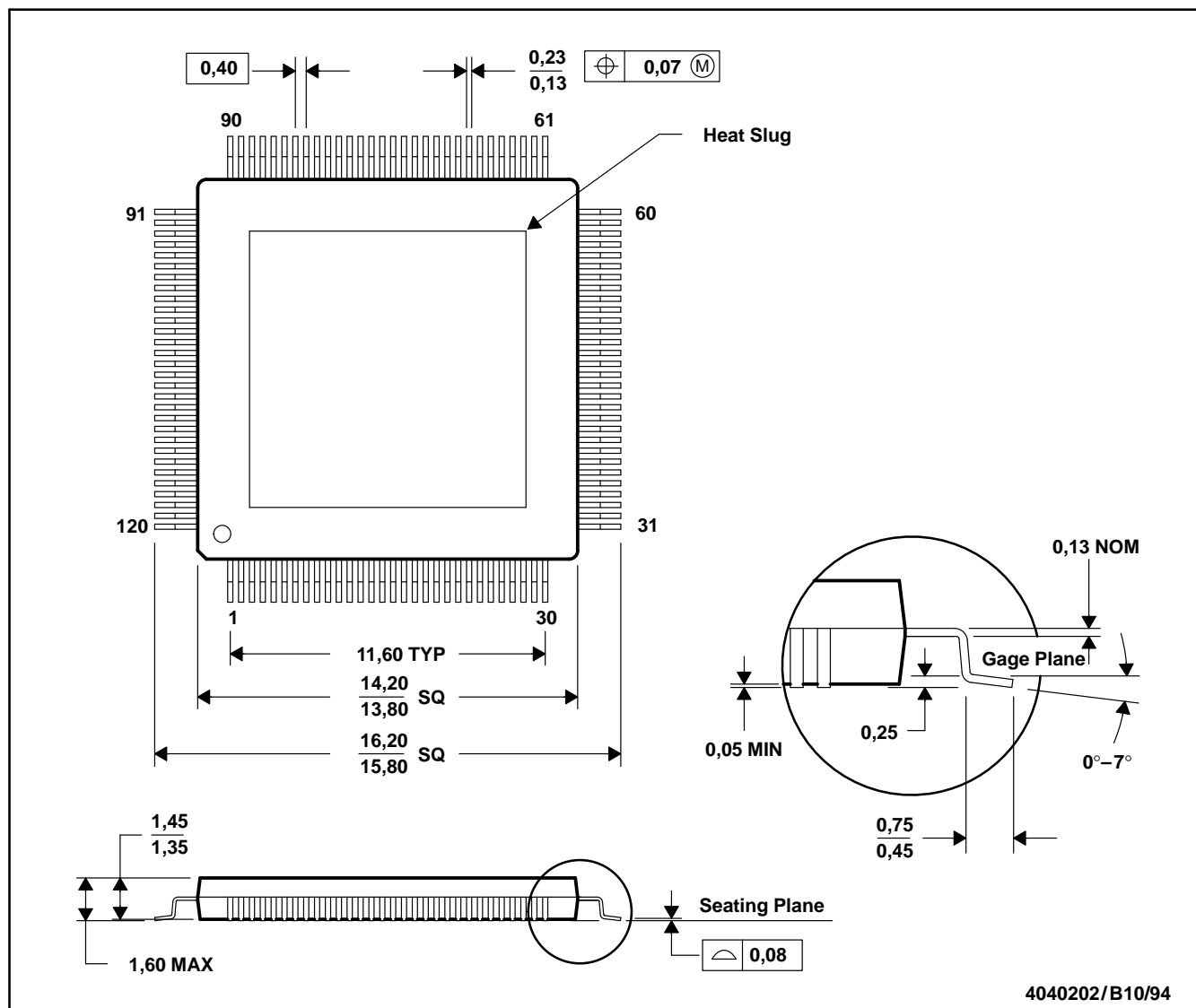


OCTOBER 1994

PCB (S-PQFP-G120)

PLASTIC QUAD FLATPACK



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Falls within JEDEC MO-136
 - Thermally enhanced molded plastic package with a heat slug (HSL)

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